



RELIABILITY REPORT
FOR
MAX5893EGK+TD
PLASTIC ENCAPSULATED DEVICES

September 15, 2017

MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

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Conclusion

The MAX5893EGK+TD successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

Table of Contents

I.Device Description	IV.Die Information
II.Manufacturing Information	V.Quality Assurance Information
III.Packaging Information	VI.Reliability Evaluation
.....Attachments	

I. Device Description

A. General

The MAX5893 programmable interpolating, modulating, 500Msps, dual digital-to-analog converter (DAC) offers superior dynamic performance and is optimized for high-performance wideband, single-carrier transmit applications. The device integrates a selectable 2x/4x/8x interpolating filter, a digital quadrature modulator, and dual 12-bit high-speed DACs on a single integrated circuit. At 30MHz output frequency and 500Msps update rate, the in-band SFDR is 84dBc while consuming 1.1W. The device also delivers 72dB ACLR for single-carrier WCDMA at a 61.44MHz output frequency. The selectable interpolating filters allow lower input data rates while taking advantage of the high DAC update rates. These linear-phase interpolation filters ease reconstruction filter requirements and enhance the passband dynamic performance. Individual offset and gain programmability allow the user to calibrate out local oscillator (LO) feedthrough and sideband suppression errors generated by analog quadrature modulators. The MAX5893 features a flm/4 digital image-reject modulator. This modulator generates a quadrature-modulated IF signal that can be presented to an analog I/Q modulator to complete the upconversion process. A second digital modulation mode allows the signal to be frequency-translated with image pairs at flm/2 or flm/4. The MAX5893 features a standard 1.8V CMOS, 3.3V tolerant data input bus for easy interface. A 3.3V SPI(tm) port is provided for mode configuration. The programmable modes include the selection of 2x/4x/8x interpolating filters, flm/2, flm/4 or no digital quadrature modulation with image rejection, channel gain and offset adjustment, and offset binary or two's complement data interface. Pin-compatible 14- and 16-bit devices are also available. Refer to the [MAX5894](#) data sheet for the 14-bit version and the [MAX5895](#) data sheet for the 16-bit version.

II. Manufacturing Information

A. Description/Function:	12-Bit, 500Msps Interpolating and Modulating Dual DAC with CMOS Inputs
B. Process:	TS18
C. Fabrication Location:	Taiwan
D. Assembly Location:	Korea, Philippines
E. Date of Initial Production:	January 20, 2005

III. Packaging Information

A. Package Type:	68-pin QFN 10x10
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2724
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 3
J. Single Layer Theta Ja:	35°C/W
K. Single Layer Theta Jc:	0.8°C/W
L. Multi Layer Theta Ja:	24°C/W
M. Multi Layer Theta Jc:	0.8°C/W

IV. Die Information

A. Dimensions:	184X179 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.23 microns (as drawn)
F. Minimum Metal Spacing:	0.23 microns (as drawn)
G. Isolation Dielectric:	SiO ₂
H. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Eric Wright (Reliability Engineering)
Brian Standley (Manager, Reliability)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% for all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 144 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 7.64 \times 10^{-9}$$

$$\lambda = 7.64 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the TS18 Process results in a FIT Rate of 0.24 @ 25C and 4.14 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing

The CD08-5 die type has been found to have all pins able to withstand an HBM transient pulse of +/-800V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA and overvoltage per JEDEC JESD78.

Table 1
Reliability Evaluation Test Results

MAX5893EGK+TD

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135C Biased Time = 192 hrs.	DC Parameters & functionality	144	0	

Note 1: Life Test Data may represent plastic DIP qualification lots.